

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BTF50060-1TEA	**Issued**	08. April 2022
MA#	MA005699808		
Package	PG-TO252-5-11	**Weight***	357.09 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	3.287	0.92	0.92	9206	9206
chip_2	inorganic material	silicon	7440-21-3	1.024	0.29	0.29	2866	2866
leadframe	inorganic material	phosphorus	7723-14-0	0.061	0.02		172	
	non noble metal	iron	7439-89-6	0.205	0.06		573	
	non noble metal	copper	7440-50-8	204.243	57.18	57.26	571963	572708
wire	non noble metal	aluminium	7429-90-5	2.420	0.68	0.68	6778	6778
encapsulation	inorganic material	zincoxide	1314-13-2	1.378	0.39		3858	
	miscellaneous	miscellaneous	-	6.888	1.93		19290	
	plastics	epoxy resin	-	20.664	5.79		57869	
	inorganic material	silicondioxide	60676-86-0	108.832	30.48	38.59	304774	385791
leadfinish	non noble metal	tin	7440-31-5	5.072	1.42	1.42	14205	14205
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.076	0.02	0.02	213	214
solder	non noble metal	tin	7440-31-5	0.056	0.02		156	
	noble metal	silver	7440-22-4	0.070	0.02		195	
	non noble metal	lead	7439-92-1	2.658	0.74	0.78	7445	7796
glue	plastics	Polyimide	26023-21-2	0.156	0.04	0.04	436	436
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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